

=> fil reg

FILE 'REGISTRY' ENTERED AT 13:37:16 ON 27 JAN 2009
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 provided by InfoChem.

STRUCTURE FILE UPDATES: 26 JAN 2009 HIGHEST RN 1096253-54-1
 DICTIONARY FILE UPDATES: 26 JAN 2009 HIGHEST RN 1096253-54-1

New CAS Information Use Policies, enter HELP USAGETERMS for details.

TSCA INFORMATION NOW CURRENT THROUGH July 5, 2008.

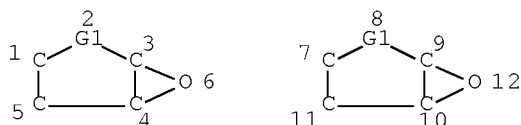
Please note that search-term pricing does apply when
 conducting SmartSELECT searches.

REGISTRY includes numerically searchable data for experimental and
 predicted properties as well as tags indicating availability of
 experimental property data in the original document. For information
 on property searching in REGISTRY, refer to:

<http://www.cas.org/support/stngen/stdoc/properties.html>

=> d sta que l15

L13 STR



REP G1=(0-4) C
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 DEFAULT ECLEVEL IS UNLIMITED

GRAPH ATTRIBUTES:
 RSPEC 1 7
 NUMBER OF NODES IS 12

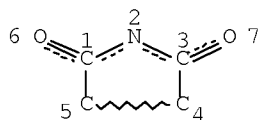
STEREO ATTRIBUTES: NONE
 L15 5706 SEA FILE=REGISTRY SSS FUL L13

100.0% PROCESSED 499629 ITERATIONS
 SEARCH TIME: 00.00.11

5706 ANSWERS

=> d sta que l28

L20 STR



NODE ATTRIBUTES:

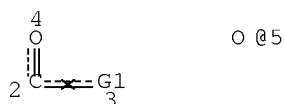
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GRAPH ATTRIBUTES:

RSPEC 1
 NUMBER OF NODES IS 7

STEREO ATTRIBUTES: NONE

L22 137753 SEA FILE=REGISTRY SSS FUL L20
 L23 STR



VAR G1=5/X

NODE ATTRIBUTES:

NSPEC IS RC AT 2
 NSPEC IS RC AT 5
 DEFAULT MLEVEL IS ATOM
 DEFAULT ECLEVEL IS UNLIMITED

GRAPH ATTRIBUTES:

RING(S) ARE ISOLATED OR EMBEDDED
 NUMBER OF NODES IS 4

STEREO ATTRIBUTES: NONE

L25 54019 SEA FILE=REGISTRY SUB=L22 SSS FUL L23
 L26 STR

G1 1 Ak @2 Id @3

VAR G1=2/3

NODE ATTRIBUTES:

DEFAULT MLEVEL IS ATOM
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 DEFAULT ECLEVEL IS UNLIMITED

GRAPH ATTRIBUTES:

RING(S) ARE ISOLATED OR EMBEDDED
 NUMBER OF NODES IS 3

STEREO ATTRIBUTES: NONE

L28 9933 SEA FILE=REGISTRY SUB=L25 SSS FUL L26

100.0% PROCESSED 54019 ITERATIONS
 SEARCH TIME: 00.00.01

9933 ANSWERS

=> fil hcaplus
 FILE 'HCAPLUS' ENTERED AT 13:37:40 ON 27 JAN 2009
 USE IS SUBJECT TO THE TERMS OF YOUR STN CUSTOMER AGREEMENT.
 PLEASE SEE "HELP USAGETERMS" FOR DETAILS.
 COPYRIGHT (C) 2009 AMERICAN CHEMICAL SOCIETY (ACS)

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FILE COVERS 1907 - 27 Jan 2009 VOL 150 ISS 5
 FILE LAST UPDATED: 26 Jan 2009 (20090126/ED)

HCAplus now includes complete International Patent Classification (IPC) reclassification data for the third quarter of 2008.

CAS Information Use Policies apply and are available at:

<http://www.cas.org/legal/infopolicy.html>

This file contains CAS Registry Numbers for easy and accurate substance identification.

=> d 190 bib abs hitstr tot

L90 ANSWER 1 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN

AN 2007:1333158 HCAPLUS Full-text

DN 147:531460

TI Positive photosensitive resin composition and porous film obtained therefrom for display

IN Hatanaka, Tadashi

PA Nissan Chemical Industries, Ltd., Japan

SO PCT Int. Appl., 32pp.

CODEN: PIXXD2

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	WO 2007132890	A1	20071122	WO 2007-JP60038	20070516
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	CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB,				
	GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM,				
	KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, MG, MK,				
	MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO,				
	RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT,				
	TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW				
	RW:				
	AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,				
	IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR, BF,				
	BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW,				

GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ,
BY, KG, KZ, MD, RU, TJ, TM

PRAI JP 2006-136798 A 20060516

AB The invention is to provide: a photosensitive resin composition from which a coating film pattern having high pattern surface water repellency even after a treatment with a plasma or the like and having insulating properties can be easily formed with high accuracy at a high throughput rate; and a cured film which is obtained from such pos. photosensitive resin composition and is suitable for use as a film material for various displays. The pos. photosensitive resin composition comprises: ingredient (A) which is an alkali-soluble resin obtained by copolymerizing (i) an unsaturated carboxylic acid with (ii) at least one compound selected from the group consisting of acrylic ester compounds, methacrylic ester compounds, maleimide compounds, acrylonitrile, maleic anhydride, styrene compounds, and vinyl compounds; ingredient (B) which is a siloxane compound having a number-average molecular weight of 100-2000; ingredient (C) which is a 1,2-quinonediazide compound; ingredient (D) which is a crosslinking compound; and a solvent (E).

IT 25085-98-7, Celloxide 2021P 149984-16-7, Epolead GT 401
176589-81-4

RL: CAT (Catalyst use); USES (Uses)

(pos. photosensitive resin composition and porous film obtained therefrom for display)

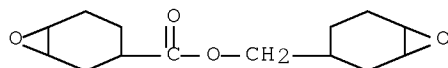
RN 25085-98-7 HCAPLUS

CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid,
7-oxabicyclo[4.1.0]hept-3-ylmethyl ester, homopolymer (CA INDEX NAME)

CM 1

CRN 2386-87-0

CMF C14 H20 O4



RN 149984-16-7 HCAPLUS

CN Epolead GT 401 (CA INDEX NAME)

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

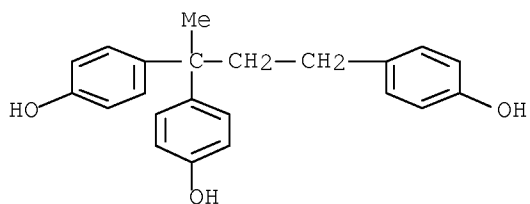
RN 176589-81-4 HCAPLUS

CN 1-Naphthalenesulfonic acid, 6-diazo-5,6-dihydro-5-oxo-, ester with
4,4',4''-(3-methyl-1-propanyl-3-ylidene)tris[phenol] (CA INDEX NAME)

CM 1

CRN 88900-12-3

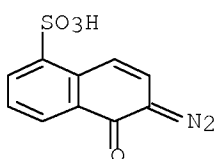
CMF C22 H22 O3



CM 2

CRN 20546-03-6

CMF C10 H6 N2 O4 S



IT 615282-97-8P, N-Cyclohexylmaleimide-2-hydroxyethyl
methacrylate-methacrylic acid-methyl methacrylate copolymer
RL: SPN (Synthetic preparation); TEM (Technical or engineered material
use); PREP (Preparation); USES (Uses)
(pos. photosensitive resin composition and porous film obtained therefrom
for display)

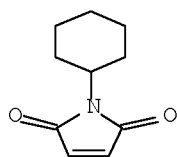
RN 615282-97-8 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with
1-cyclohexyl-1H-pyrrole-2,5-dione, 2-hydroxyethyl 2-methyl-2-propenoate
and methyl 2-methyl-2-propenoate (CA INDEX NAME)

CM 1

CRN 1631-25-0

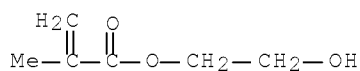
CMF C10 H13 N O2



CM 2

CRN 868-77-9

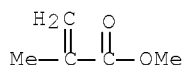
CMF C6 H10 O3



CM 3

CRN 80-62-6

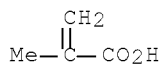
CMF C5 H8 O2



CM 4

CRN 79-41-4

CMF C4 H6 O2



RE.CNT 25 THERE ARE 25 CITED REFERENCES AVAILABLE FOR THIS RECORD
ALL CITATIONS AVAILABLE IN THE RE FORMAT

L90 ANSWER 2 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN

AN 2007:1027810 HCAPLUS Full-text

DN 147:344946

TI Polyamic acid composition for forming insulating layer and insulating film

IN Kondo, Fumitaka; Ootaniuchi, Yuuko

PA Japan

SO U.S. Pat. Appl. Publ., 63pp.

CODEN: USXXCO

DT Patent

LA English

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	US 20070213502	A1	20070913	US 2007-715932	20070309
	JP 2007270121	A	20071018	JP 2006-319672	20061128
	KR 2007092624	A	20070913	KR 2007-21941	20070306
	KR 854003	B1	20080825		
PRAI	JP 2006-63596	A	20060309		
	JP 2006-319672	A	20061128		

AB A composition for forming an insulating layer of an electronic device is provided, and the composition contains at least one polymer selected from a polyamic acid and a derivative of a polyamic acid, and a compound having a functional group capable of reacting with a carboxyl group contained in a constitutional unit of the polymer.

IT ~~87848-87-1P~~ Glycidyl methacrylate-N-phenylmaleimide copolymer

RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM
(Technical or engineered material use); PREP (Preparation); USES (Uses)

(polyamic acid composition for forming insulating layer and insulating film)

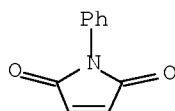
RN 87848-87-1 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-oxiranylmethyl ester, polymer with
1-phenyl-1H-pyrrole-2,5-dione (CA INDEX NAME)

CM 1

CRN 941-69-5

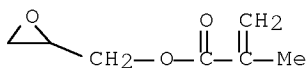
CMF C10 H7 N O2



CM 2

CRN 106-91-2

CMF C7 H10 O3

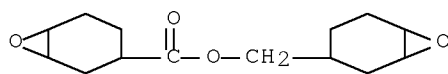


IT 2386-87-0

RL: TEM (Technical or engineered material use); USES (Uses)

(polyamic acid composition for forming insulating layer and insulating film)

RN 2386-87-0 HCAPLUS

CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid,
7-oxabicyclo[4.1.0]hept-3-ylmethyl ester (CA INDEX NAME)

L90 ANSWER 3 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN

AN 2005:99716 HCAPLUS Full-text

DN 142:186553

TI Positive type photosensitive resin composition showing excellent physical
properties suitable for display

IN Tsuji, Shinsuke; Iinuma, Yosuke; Arase, Shinya

PA Nissan Chemical Industries, Ltd., Japan

SO PCT Int. Appl., 42 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

FAN.CNT 1

PATENT NO.

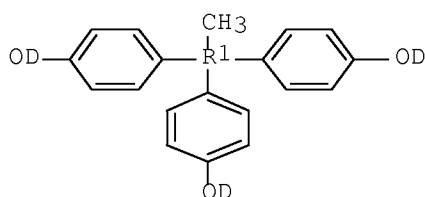
KIND

DATE

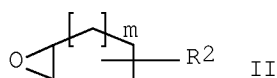
APPLICATION NO.

DATE

PI	WO 2005010615	A1	20050203	WO 2004-JP11103	20040728 <--
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	CN 1816774	A	20060809	CN 2004-80019174	20040728 <--
	KR 2006038930	A	20060504	KR 2005-722417	20051123 <--
	US 20060211797	A1	20060921	US 2006-565977	20060126 <--
PRAI	JP 2003-280625	A	20030728	<--	
	WO 2004-JP11103	W	20040728	<--	
OS	MARPAT 142:186553				
GI					



I



II

AB A pos. type photosensitive resin composition which can form a cured film excellent in processing resistance including heat resistance, solvent resistance, and resistance to long-term burning and in transparency. It is excellent in photosensitive properties including resolution and sensitivity, has high storage stability, and has a wide process margin. When used for producing liquid-crystal displays, the composition has such high reliability that use of the composition does not lead to deterioration in elec. properties. The pos. type photosensitive resin composition is characterized by comprising: an alkali-soluble resin which is a copolymer formed from monomers comprising an unsatd. carboxylic acid derivative and an N-substituted maleimide as essential ingredients and has a number-average mol. weight of 2,000 to 20,000; a 1,2-quinonediazide compound represented by the general formula I (D = H, organic group having 1,2-quinonediazide group; R1 = C, tetravalent organic group); and a crosslinking compound represented by the general formula II (n = 2-10; m = 0-4; R2 = n-valent organic group), which is contained in an amount of 5 to 50 parts by weight based on the alkali-soluble resin.

IT 28136-81-4P, 2-Hydroxyethyl methacrylate-methacrylic acid-methyl methacrylate copolymer 116945-38-1P, 2-Hydroxyethyl methacrylate-methacrylic acid-methyl methacrylate-N-phenylmaleimide copolymer 615282-97-8P, N-Cyclohexylmaleimide-2-hydroxyethyl methacrylate-methacrylic acid-methyl methacrylate copolymer 832738-77-9P, N-Cyclohexylmaleimide-diethyl maleate-hydroxybutyl methacrylate-methacrylic acid copolymer

RL: PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(pos. type photosensitive resin composition showing excellent phys.
properties suitable for display)

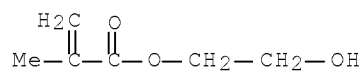
RN 28136-81-4 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with 2-hydroxyethyl
2-methyl-2-propenoate and methyl 2-methyl-2-propenoate (CA INDEX NAME)

CM 1

CRN 868-77-9

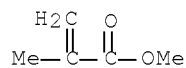
CMF C6 H10 O3



CM 2

CRN 80-62-6

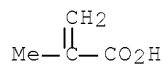
CMF C5 H8 O2



CM 3

CRN 79-41-4

CMF C4 H6 O2



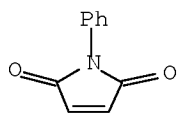
RN 116945-38-1 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with 2-hydroxyethyl
2-methyl-2-propenoate, methyl 2-methyl-2-propenoate and
1-phenyl-1H-pyrrole-2,5-dione (9CI) (CA INDEX NAME)

CM 1

CRN 941-69-5

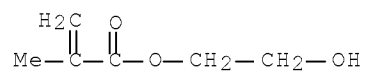
CMF C10 H7 N O2



CM 2

CRN 868-77-9

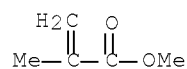
CMF C6 H10 O3



CM 3

CRN 80-62-6

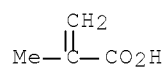
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CM 4

CRN 79-41-4

CMF C4 H6 O2



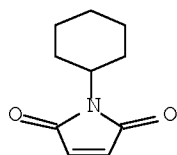
RN 615282-97-8 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with
1-cyclohexyl-1H-pyrrole-2,5-dione, 2-hydroxyethyl 2-methyl-2-propenoate
and methyl 2-methyl-2-propenoate (CA INDEX NAME)

CM 1

CRN 1631-25-0

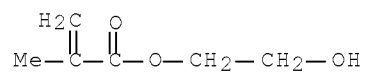
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CM 2

CRN 868-77-9

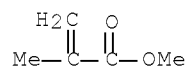
CMF C6 H10 O3



CM 3

CRN 80-62-6

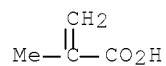
CMF C5 H8 O2



CM 4

CRN 79-41-4

CMF C4 H6 O2



RN 832738-77-9 HCAPLUS

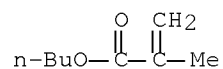
CN 2-Butenedioic acid (2Z)-, diethyl ester, polymer with
1-cyclohexyl-1H-pyrrole-2,5-dione, hydroxybutyl 2-methyl-2-propenoate and
2-methyl-2-propenoic acid (9CI) (CA INDEX NAME)

CM 1

CRN 29721-79-7

CMF C8 H14 O3

CCI IDS

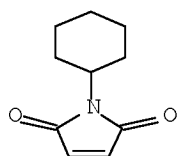


D1-OH

CM 2

CRN 1631-25-0

CMF C10 H13 N O2

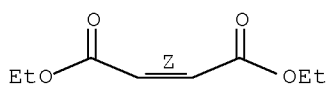


CM 3

CRN 141-05-9

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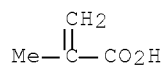
Double bond geometry as shown.



CM 4

CRN 79-41-4

CMF C4 H6 O2



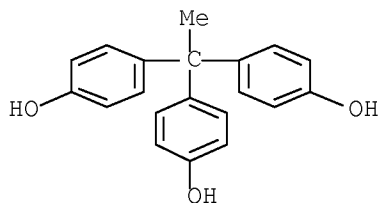
IT 27955-94-8 110726-28-8 832738-79-1

RL: TEM (Technical or engineered material use); USES (Uses)

(pos. type photosensitive resin composition showing excellent phys. properties suitable for display)

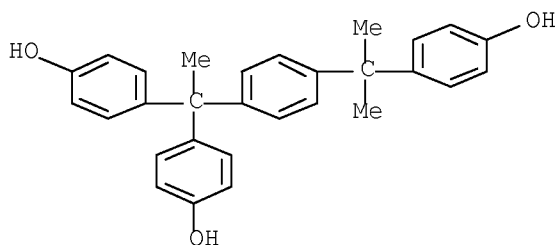
RN 27955-94-8 HCAPLUS

CN Phenol, 4,4',4''-ethylidynetris- (CA INDEX NAME)

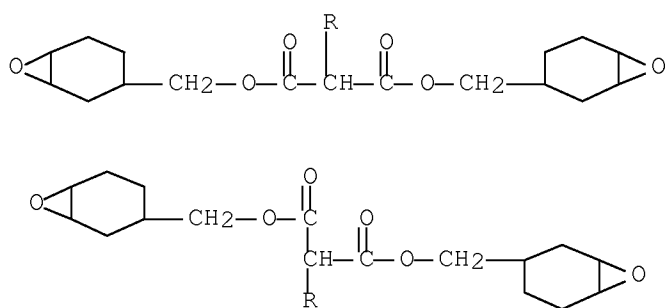


RN 110726-28-8 HCAPLUS

CN Phenol, 4,4'-[1-[4-[1-(4-hydroxyphenyl)-1-methylethyl]phenyl]ethylidene]bis- (CA INDEX NAME)



RN 832738-79-1 HCAPLUS
 CN 2,2,3,3-Butanetetracarboxylic acid,
 1,2,3,4-tetrakis(7-oxabicyclo[4.1.0]hept-3-ylmethyl) ester (CA INDEX
 NAME)



RE.CNT 12 THERE ARE 12 CITED REFERENCES AVAILABLE FOR THIS RECORD
 ALL CITATIONS AVAILABLE IN THE RE FORMAT

L90 ANSWER 4 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN

AN 2004:271645 HCAPLUS Full-text

DN 140:294934

TI Cellulose acylate composite films, their manufacture, and their uses in
 optical films, liquid crystal displays, and photographic materials

IN Kato, Eiichi

PA Fuji Photo Film Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 48 pp.

CODEN: JKXXAF

DT Patent

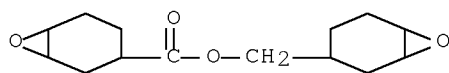
LA Japanese

FAN.CNT 1

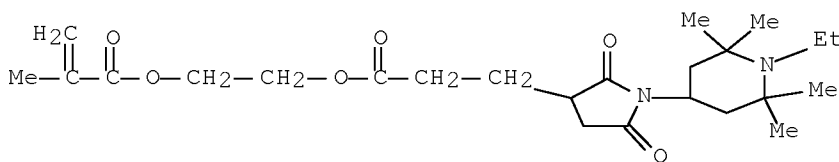
	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2004099775	A	20040402	JP 2002-264588	20020910
PRAI	JP 2002-264588		20020910		

AB The films are manufactured by casting cellulose acylate compns. containing radically-polymerizable monomers, cationically-polymerizable monomers, and photopolymn. initiators and irradiating the compns. with electron beam (sic). Also claimed are optical films and liquid crystal displays using the films and Ag halide photog. materials using the films with thickness 30-250 μ m as supports. The films show low haze, high tear strength, good weatherability, and neither contamination with foreign substances nor stains. A polarizer film prepared by laminating both sides of an iodine-adsorbed PVA-based polarizer with a pair of the composite cellulose triacetate films shows high durability.

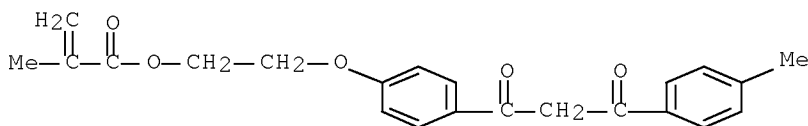
IT 25085-98-7P 676265-28-4P 676265-48-8P
 RL: IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); POF (Polymer in formulation); PYP (Physical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
 (manufacture of cellulose acylate films for LCD, photog. materials, etc., from dopes containing radically-polymerizable monomers, cationically-polymerizable monomers, and photoinitiators)
 RN 25085-98-7 HCAPLUS
 CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid, 7-oxabicyclo[4.1.0]hept-3-ylmethyl ester, homopolymer (CA INDEX NAME)
 CM 1
 CRN 2386-87-0
 CMF C14 H20 O4



RN 676265-28-4 HCAPLUS
 CN 3-Pyrrolidinepropanoic acid, 1-(1-ethyl-2,2,6,6-tetramethyl-4-piperidinyl)-2,5-dioxo-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester, polymer with cyclohexylmethyl 2-methyl-2-propenoate and 2-[4-[3-(4-methylphenyl)-1,3-dioxopropyl]phenoxy]ethyl 2-methyl-2-propenoate (9CI) (CA INDEX NAME)
 CM 1
 CRN 658059-99-5
 CMF C24 H38 N2 O6



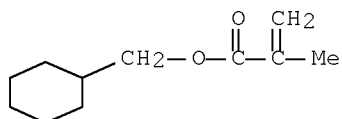
CM 2
 CRN 658059-98-4
 CMF C22 H22 O5



CM 3

CRN 16868-16-9

CMF C11 H18 O2



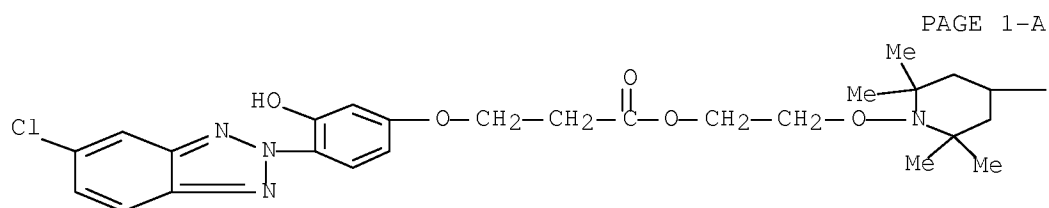
RN 676265-48-8 HCAPLUS

CN 7-Oxabicyclo[4.1.0]heptane-3-acetic acid,
 5-(7-oxabicyclo[4.1.0]hept-3-yloxy)-5-oxopentyl ester, polymer with
 2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl 2-methyl-2-propenoate and
 2-[[2,2,6,6-tetramethyl-4-(oxiranylmethoxy)-1-piperidinyl]oxy]ethyl
 3-[4-(5-chloro-2H-benzotriazol-2-yl)-3-hydroxyphenoxy]propanoate (9CI)
 (CA INDEX NAME)

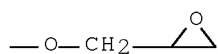
CM 1

CRN 676265-47-7

CMF C29 H37 Cl N4 O7



PAGE 1-A

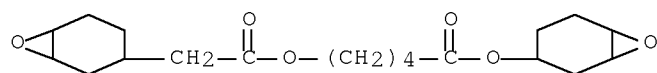


PAGE 1-B

CM 2

CRN 676265-46-6

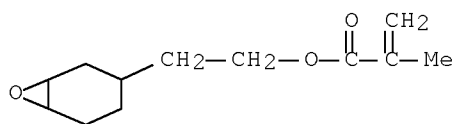
CMF C19 H28 O6



CM 3

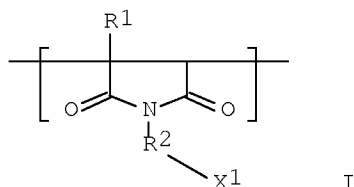
CRN 59620-20-1

CMF C12 H18 O3



L90 ANSWER 5 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN
 AN 1998:651086 HCAPLUS Full-text
 DN 129:331577
 OREF 129:67625a,67628a
 TI Alkali-developable curable maleimide polymer compositions with high glass transition temperature
 IN Akutsu, Mitsuo; Tominaga, Nobuhide; Saito, Seiichi
 PA Asahi Denka Kogyo K. K., Japan
 SO Jpn. Kokai Tokkyo Koho, 11 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 10265649	A	19981006	JP 1997-74041	19970326
	JP 3770689	B2	20060426		
PRAI	JP 1997-74041		19970326		
GI					



AB Title compns. contain (A) copolymers comprising repeating units I (R1 = H, Me; R2 = C1-18 alkylene, cycloalkylene, arylene; X1 = H, C1-4 alkyl, CO2H) 5-95, R3C[C6H4(CH2OC6H4)nX2]CH2 (R3 = H, Me; X2 = H, C1-4 alkyl, CO2H; n = 0, 1) 5-95, and CR4X3CH2 (R4 = H, Me; X3 = CO2H, CONR5R6, CO2R7; R5, R6 = H, C1-8 alkyl; R7 = C1-4 alkyl) 0-50%, and (B) compds. having ≥ 2 epoxy groups. The compns. are useful for coatings, adhesives, insulator resists for integrated circuits, etc. Thus, a mixture of N-(p-carboxyphenyl)maleimide-styrene copolymer 20, 2,2-bis(3,4-epoxycyclohexyl)propane 3.7, dipentaerythritol hexaacrylate 11.9, triazine photopolymn. initiator 1.8, and cyclohexanone 142 parts was applied on an Al plate, and cured by UV to give a product showing peeling strength 1.9 kg/cm, volume resistivity $1.9 \times 10^6 \Omega\text{-cm}$, specific inductive capacity (1 MHz) 3.6, Tg 400°, and good alkali developability.

IT 215101-80-7P 215101-81-8P 215101-83-0P
 215101-84-1P 215101-85-2P 215101-86-3P

RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
 (alkali-developable curable maleimide polymer compns. with high glass transition temperature)

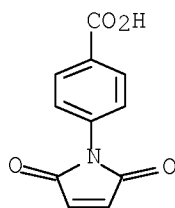
RN 215101-80-7 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene and 3,3'-(1-methylethylidene)bis[7-oxabicyclo[4.1.0]heptane] (9CI) (CA INDEX NAME)

CM 1

CRN 17057-04-4

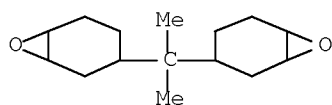
CMF C11 H7 N O4



CM 2

CRN 14513-43-0

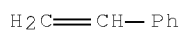
CMF C15 H24 O2



CM 3

CRN 100-42-5

CMF C8 H8



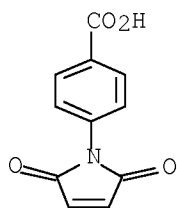
RN 215101-81-8 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene and 2,2'-[(1-methylethylidene)bis(4,1-phenyleneoxymethylene)]bis[oxirane] (9CI) (CA INDEX NAME)

CM 1

CRN 17057-04-4

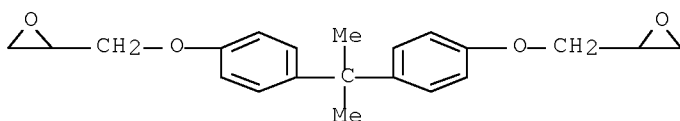
CMF C11 H7 N O4



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CRN 1675-54-3

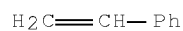
CMF C21 H24 O4



CM 3

CRN 100-42-5

CMF C8 H8



RN 215101-83-0 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene and α -[[methyl(oxiranylmethoxy)phenyl]methyl]- ω -[[methyl(oxiranylmethoxy)phenyl]poly[[methyl(oxiranylmethoxy)phenylene]methylene] (9CI) (CA INDEX NAME)

CM 1

CRN 83381-31-1

CMF (C11 H12 O2)_n C21 H24 O4

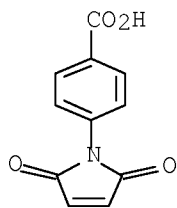
CCI IDS, PMS, MAN

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CRN 17057-04-4

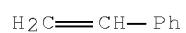
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CM 3

CRN 100-42-5

CMF C8 H8



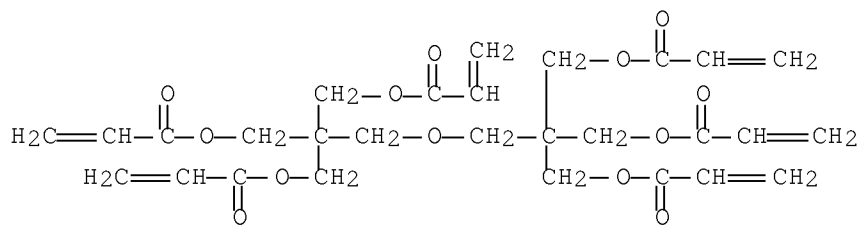
RN 215101-84-1 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene, 3,3'-(1-methylethylidene)bis[7-oxabicyclo[4.1.0]heptane] and 2-[[3-[(1-oxo-2-propenyl)oxy]-2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 29570-58-9

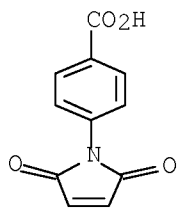
CMF C28 H34 O13



CM 2

CRN 17057-04-4

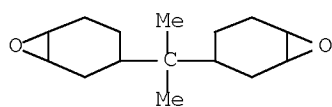
CMF C11 H7 N O4



CM 3

CRN 14513-43-0

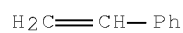
CMF C15 H24 O2



CM 4

CRN 100-42-5

CMF C8 H8



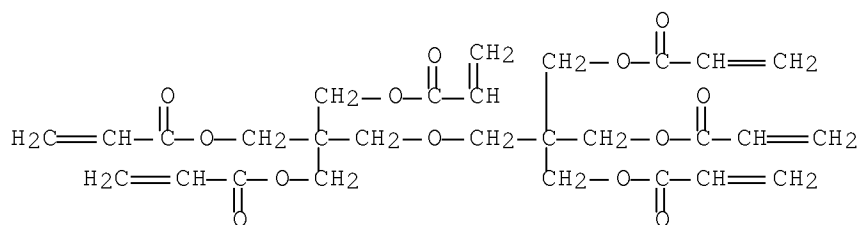
RN 215101-85-2 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene, 2,2'-[(1-methylethylidene)bis(4,1-phenyleneoxymethylene)]bis[oxirane] and 2-[[3-[(1-oxo-2-propenyl)oxy]-2,2-bis[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 29570-58-9

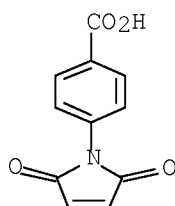
CMF C28 H34 O13



CM 2

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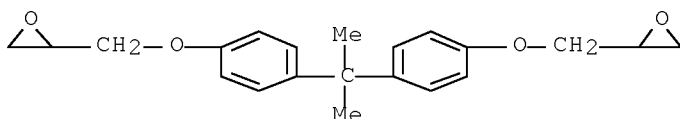
CMF C11 H7 N O4



CM 3

CRN 1675-54-3

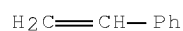
CMF C21 H24 O4



CM 4

CRN 100-42-5

CMF C8 H8



RN 215101-86-3 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene, α -[[methyl(oxiranylmethoxy)phenyl]methyl]- ω -[[methyl(oxiranylmethoxy)phenyl]poly[[methyl(oxiranylmethoxy)phenylene]methylene] and 2-[[3-[(1-oxo-2-propenyl)oxy]-2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 83381-31-1

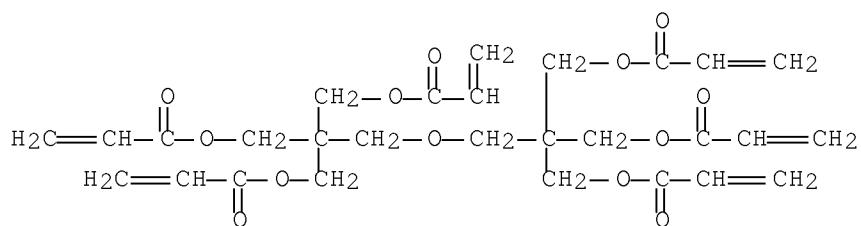
CMF (C11 H12 O2)_n C21 H24 O4

CCI IDS, PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

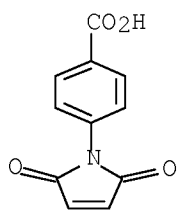
CM 2

CRN 29570-58-9
CMF C28 H34 O13



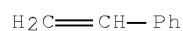
CM 3

CRN 17057-04-4
CMF C11 H7 N O4



CM 4

CRN 100-42-5
CMF C8 H8



IT 130055-33-3P 194472-63-4P 194472-64-5P
194472-65-6P

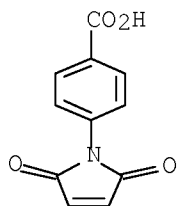
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(alkali-developable curable maleimide polymer compns. with high glass transition temperature)

RN 130055-33-3 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene and methyl 2-methyl-2-propenoate (9CI) (CA INDEX NAME)

CM 1

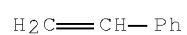
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CMF C11 H7 N O4



CM 2

CRN 100-42-5

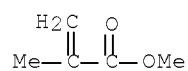
CMF C8 H8



CM 3

CRN 80-62-6

CMF C5 H8 O2



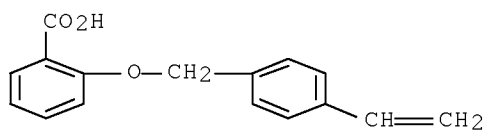
RN 194472-63-4 HCAPLUS

CN Benzoic acid, 2-[(4-ethenylphenyl)methoxy]-, polymer with
1-phenyl-1H-pyrrole-2,5-dione (9CI) (CA INDEX NAME)

CM 1

CRN 194472-62-3

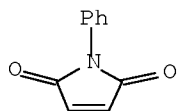
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CM 2

CRN 941-69-5

CMF C10 H7 N O2



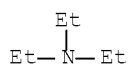
RN 194472-64-5 HCAPLUS

CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene, compd. with N,N-diethylethanamine (9CI) (CA INDEX NAME)

CM 1

CRN 121-44-8

CMF C6 H15 N



CM 2

CRN 124489-29-8

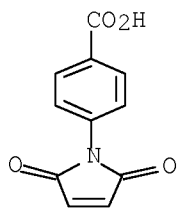
CMF (C11 H7 N O4 . C8 H8)x

CCI PMS

CM 3

CRN 17057-04-4

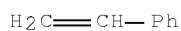
CMF C11 H7 N O4



CM 4

CRN 100-42-5

CMF C8 H8



RN 194472-65-6 HCAPLUS

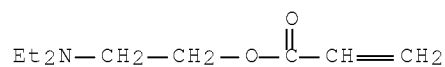
CN Benzoic acid, 4-(2,5-dihydro-2,5-dioxo-1H-pyrrol-1-yl)-, polymer with ethenylbenzene, compd. with 2-(diethylamino)ethyl 2-propenoate (9CI) (CA

INDEX NAME)

CM 1

CRN 2426-54-2

CMF C9 H17 N O2



CM 2

CRN 124489-29-8

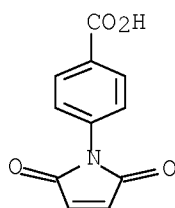
CMF (C11 H7 N O4 . C8 H8)x

CCI PMS

CM 3

CRN 17057-04-4

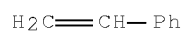
CMF C11 H7 N O4



CM 4

CRN 100-42-5

CMF C8 H8



L90 ANSWER 6 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN
 AN 1995:424967 HCAPLUS Full-text
 DN 122:252127
 OREF 122:45785a,45788a
 TI Alkali-developable photocurable resin composition
 IN Okuo, Masami; Enomoto, Hiroyuki; Koma, Toshio
 PA Nippon Oils & Fats Co Ltd, Japan
 SO Jpn. Kokai Tokkyo Koho, 10 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 07003116	A	19950106	JP 1993-172757	19930618
PRAI	JP 1993-172757		19930618		
AB	The composition contains (a) 100 parts copolymer consisting of 1-95 weight% epoxy-containing monomer, 5-50 weight% hydroxyphenyl-containing monomer, and 0-94 weight% other copolymerizable monomer, (b) 0.01-20 parts proton-generating photoreactive agent, and (c) 0-200 parts reactive diluent. The composition showed high sensitivity and good heat resistance.				
IT	162381-20-6P RL: PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (alkali-developable photocurable resin composition)				
RN	162381-20-6 HCAPLUS				
CN	2-Propenoic acid, 2-methyl-, 2-(hydroxyphenoxy)ethyl ester, polymer with 1-cyclohexyl-1H-pyrrole-2,5-dione, ethenylbenzene, ethenylphenol, 2-hydroxypropyl 2-methyl-2-propenoate and oxiranylmethyl 2-methyl-2-propenoate (9CI) (CA INDEX NAME)				

CM 1

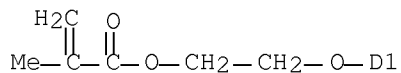
CRN 162381-19-3

CMF C12 H14 O4

CCI IDS



D1-OH



CM 2

CRN 31257-96-2

CMF C8 H8 O

CCI IDS



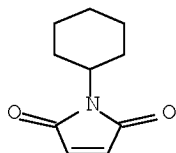
D1-OH

D1-CH=CH₂

CM 3

CRN 1631-25-0

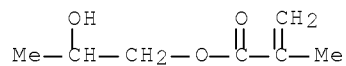
CMF C10 H13 N O2



CM 4

CRN 923-26-2

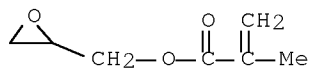
CMF C7 H12 O3



CM 5

CRN 106-91-2

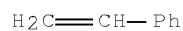
CMF C7 H10 O3



CM 6

CRN 100-42-5

CMF C8 H8

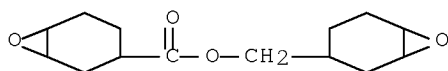


IT 2386-87-0 25085-98-7, Cyracure UVR 6110

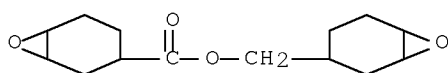
RL: TEM (Technical or engineered material use); USES (Uses)
 (alkali-developable photocurable resin composition)

RN 2386-87-0 HCAPLUS

CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid,
 7-oxabicyclo[4.1.0]hept-3-ylmethyl ester (CA INDEX NAME)



RN 25085-98-7 HCAPLUS
 CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid,
 7-oxabicyclo[4.1.0]hept-3-ylmethyl ester, homopolymer (CA INDEX NAME)
 CM 1
 CRN 2386-87-0
 CMF C14 H20 O4



L90 ANSWER 7 OF 7 HCAPLUS COPYRIGHT 2009 ACS on STN
 AN 1984:69234 HCAPLUS Full-text
 DN 100:69234
 OREF 100:10559a,10562a
 TI Heat-resistant electric insulators
 PA Mitsubishi Electric Corp., Japan
 SO Jpn. Kokai Tokkyo Koho, 5 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 58084812	A	19830521	JP 1981-184878	19811117
	JP 01025326	B	19890517		
PRAI	JP 1981-184878		19811117		

AB Thermosetting resins for heat-resistant elec. insulators are prepared from 20-95 parts 1:0.8-1.5 (equivalent) blends of polyepoxides and unsatd. monocarboxylic acids and 5-80 parts 5-95:5-95 blends of prepolymers (from Nadic anhydride, diamines, and tetracarboxylic dianhydrides) and polymaleimides. Thus, a composition of DER 332 170, acrylic acid 72, polymaleimide (from MDA 150 and maleic anhydride) 121, and prepolymer [from Nadic anhydride, 4,4'-methylenedianiline, 1,4-phenylenediamine, and 5-(2,5-dioxotetrahydrofurfuryl)-3-methyl-3-cyclohexene-1,2-dicarboxylic anhydride] 60 g was heated 15 and 8 h at 150 and 220°, resp., to give a copolymer [88644-44-4] with flexural strength 17.0 and 14.0 kg/mm² at 25 and 200°, resp., volume resistivity 1.8 + 10¹⁶ and 8.0 + 10¹³ Ω-cm, resp., heat-distortion temperature >200°, and weight loss after 500 h in air at 240° 3.5%.

IT 88644-44-4P 88668-55-7P 88729-51-5P
 RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses) (elec. insulators, heat-resistant, manufacture of)

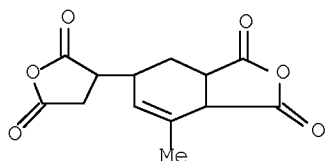
RN 88644-44-4 HCAPLUS
 CN 2-Propenoic acid, polymer with 1,4-benzenediamine, (chloromethyl)oxirane, formaldehyde, 4,4'-methylenebis[benzenamine], 4,4'-(1-methylethylidene)bis[phenol], 1-phenyl-1H-pyrrole-2,5-dione,

(3 α , 4 α , 7 α , 7 $\alpha\alpha$)-3 α , 4, 7, 7 α -tetrahydro-4, 7-methanoisobenzofuran-1, 3-dione and
3 α , 4, 5, 7 α -tetrahydro-7-methyl-5-(tetrahydro-2, 5-dioxo-3-furanyl)-1, 3-isobenzofurandione (9CI) (CA INDEX NAME)

CM 1

CRN 73003-90-4

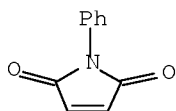
CMF C13 H12 O6



CM 2

CRN 941-69-5

CMF C10 H7 N O2

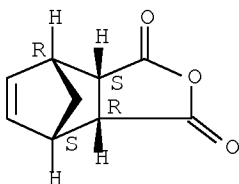


CM 3

CRN 129-64-6

CMF C9 H8 O3

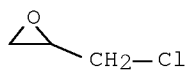
Relative stereochemistry.



CM 4

CRN 106-89-8

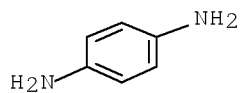
CMF C3 H5 Cl O



CM 5

CRN 106-50-3

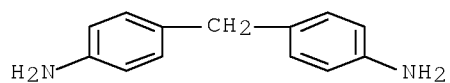
CMF C6 H8 N2



CM 6

CRN 101-77-9

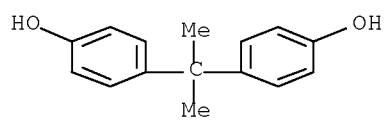
CMF C13 H14 N2



CM 7

CRN 80-05-7

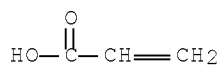
CMF C15 H16 O2



CM 8

CRN 79-10-7

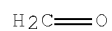
CMF C3 H4 O2



CM 9

CRN 50-00-0

CMF C H2 O



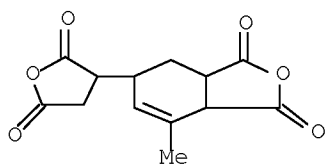
RN 88668-55-7 HCAPLUS

CN 2-Propenoic acid, polymer with 1,4-benzenediamine, (chloromethyl)oxirane, 4,4'-methylenebis[benzenamine], 1,1'-(methylenedi-4,1-phenylene)bis[1H-pyrrole-2,5-dione], 4,4'-(1-methylethylidene)bis[phenol], (3 α ,4 α ,7 α ,7 α)-3 α ,4,7,7 α -tetrahydro-4,7-methanoisobenzofuran-1,3-dione and 3 α ,4,5,7 α -tetrahydro-7-methyl-5-(tetrahydro-2,5-dioxo-3-furanyl)-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

CM 1

CRN 73003-90-4

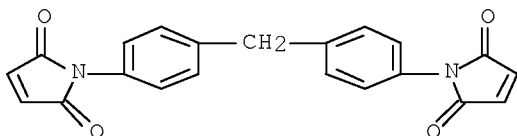
CMF C13 H12 O6



CM 2

CRN 13676-54-5

CMF C21 H14 N2 O4

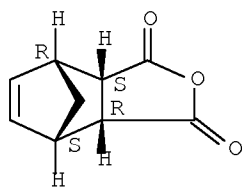


CM 3

CRN 129-64-6

CMF C9 H8 O3

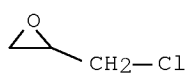
Relative stereochemistry.



CM 4

CRN 106-89-8

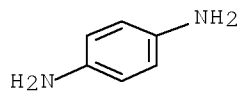
CMF C3 H5 Cl O



CM 5

CRN 106-50-3

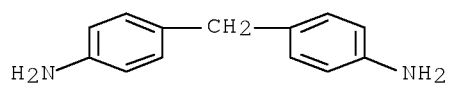
CMF C6 H8 N2



CM 6

CRN 101-77-9

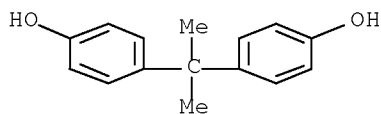
CMF C13 H14 N2



CM 7

CRN 80-05-7

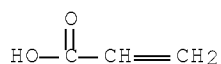
CMF C15 H16 O2



CM 8

CRN 79-10-7

CMF C3 H4 O2



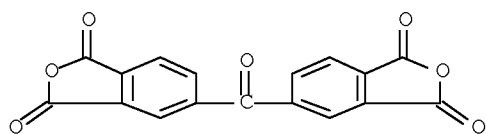
RN 88729-51-5 HCAPLUS

CN 7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid,
 7-oxabicyclo[4.1.0]hept-3-ylmethyl ester, polymer with
 5,5'-carbonylbis[1,3-isobenzofurandione], formaldehyde,
 4,4'-methylenebis[cyclohexanamine], 1-phenyl-1H-pyrrole-2,5-dione,
 2-propenoic acid and (3 α ,4 α ,7 α ,7 α)-3a,4,7,7a-
 tetrahydro-4,7-methanoisobenzofuran-1,3-dione (9CI) (CA INDEX NAME)

CM 1

CRN 2421-28-5

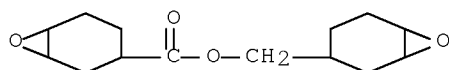
CMF C17 H6 O7



CM 2

CRN 2386-87-0

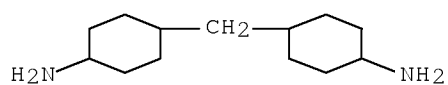
CMF C14 H20 O4



CM 3

CRN 1761-71-3

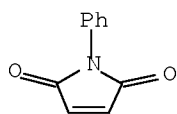
CMF C13 H26 N2



CM 4

CRN 941-69-5

CMF C10 H7 N O2

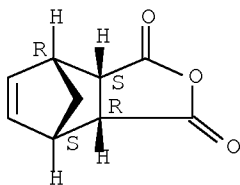


CM 5

CRN 129-64-6

CMF C9 H8 O3

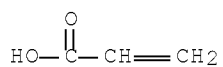
Relative stereochemistry.



CM 6

CRN 79-10-7

CMF C3 H4 O2



CM 7

CRN 50-00-0

CMF C H2 O

H₂C=O

=> d his

(FILE 'HOME' ENTERED AT 12:47:07 ON 27 JAN 2009)
SET COST OFF

FILE 'HCAPLUS' ENTERED AT 12:47:16 ON 27 JAN 2009

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L1      1 S US20060211797/PN OR (US2006-565977# OR WO2004-JP11103 OR JP20
      E TSUJI/AU
      E TSUJI S/AU
L2      319 S E3
      E TSUJI SHIN/AU
L3      30 S E12
      E TSUJI NAME/AU
L4      28 S E4
      E SHINSUKE/AU
L5      3 S E9
      E SHIN SUKE/AU
      E IINUMA/AU
L6      19 S E98,E156,E157,E178
      E YOSUKE/AU
      E ARASE/AU
L7      45 S E58,E65
      E SHINYA/AU
L8      12 S E3,E4
      E NISSAN/CO
L9      4283 S E19-E42/CO,PA,CS
      E E39+ALL
L10     4269 S E2+RT OR E2-E13/PA,CS
L11     4477 S (NISSAN?(L)CHEM?)/CO,PA,CS
      SEL RN L1
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FILE 'REGISTRY' ENTERED AT 12:51:45 ON 27 JAN 2009

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L12     7 S E1-E7
L13     STR
L14     35 S L13
L15     5706 S L13 FUL
      SAV TEMP L15 BERN565A/A
L16     1044 S L15 NOT PMS/CI
L17     1043 S L16 NOT MXS/CI
L18     1015 S L17 NOT (UNSPECIFIED OR COMPD OR WITH OR CONJUGATE OR LABELED
L19     4691 S L15 NOT L18
L20     STR
L21     50 S L20
L22     137753 S L20 FUL
L23     STR
L24     50 S L23 SAM SUB=L22
L25     54019 S L23 FUL SUB=L22
L26     STR
L27     50 S L26 SAM SUB=L25
L28     9933 S L26 FUL SUB=L25
      SAV TEMP L28 BERN565B/A
L29     STR L23
L30     50 S L29 SAM SUB=L28
L31     6027 S L28 AND PMS/CI
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L32 3906 S L28 NOT L31

FILE 'HCAPLUS' ENTERED AT 13:02:32 ON 27 JAN 2009

L33 4866 S L18
L34 4188 S L31
L35 6 S L33 AND L34
L36 5796 S L19
L37 10151 S L33,L36
L38 5822 S L32
L39 9742 S L34,L38
L40 25 S L37 AND L39
L41 2 S L40 AND (?QUINONE DIAZID? OR ?QUINONEDIAZID?)
L42 2 S L1-L11 AND L40
L43 2 S L41,L42
L44 25 S L40-L43

FILE 'REGISTRY' ENTERED AT 13:04:26 ON 27 JAN 2009

FILE 'HCAPLUS' ENTERED AT 13:04:26 ON 27 JAN 2009

L45 TRA L44 1- RN : 870 TERMS

FILE 'REGISTRY' ENTERED AT 13:04:27 ON 27 JAN 2009

L46 870 SEA L45
L47 39 S L46 AND L15
L48 7 S L47 AND L18
L49 32 S L47 NOT L48
L50 5 S L49 AND 1/NC
L51 49 S L46 AND L28
L52 43 S L51 NOT L47-L50
L53 35 S L52 AND PMS/CI
L54 15 S L53 AND (C7H10O3 OR C3H4O2 OR C9H17NO2 OR C4H6O2 OR C4H2O3 OR
L55 34 S L51 NOT L54
L56 6 S L55 AND (C35H26N2O6 OR C15H24O2 OR C14H22O7 OR C18H26O6)
L57 4 S L56 NOT C11H7NO4
L58 300 S L46 AND 46.150.18/RID AND NR>=3
L59 2 S L12 AND L58
L60 63 S L58 AND PHENOL
L61 3 S L60 AND (C20H18O3 OR C27H26O6 OR C29H28O3)
L62 237 S L58 NOT L59-L61
L63 205 S L62 AND O>=3
L64 32 S L62 NOT L63
L65 14 S 1 2 QUINONE
L66 0 S L46 AND 46.150.6/RID
L67 5 S L46 AND DIAZ?
L68 182 S L46 AND N/ELS NOT L47-L67

FILE 'HCAPLUS' ENTERED AT 13:25:29 ON 27 JAN 2009

L69 TRA L43 1- RN : 16 TERMS

FILE 'REGISTRY' ENTERED AT 13:25:29 ON 27 JAN 2009

L70 16 SEA L69
L71 11 S L70 NOT SI/ELS
L72 3 S L71 AND L54,L57
L73 3 S L71 AND NC4/ES
L74 3 S L72,L73
L75 2 S L71 AND L48,L50
L76 3 S L71 AND 46.150.18/RID NOT L74,L75

FILE 'HCAPLUS' ENTERED AT 13:26:57 ON 27 JAN 2009

L77 10 S L44 AND L54,L75,L74

L78 5 S L77 AND L48,L50,L75
 L79 2 S L78 AND L61,L76
 L80 2 S L79,L43

FILE 'REGISTRY' ENTERED AT 13:28:06 ON 27 JAN 2009

L81 3 S L71 NOT L72-L76
 L82 2 S L81 AND PMS/CI

FILE 'HCAPLUS' ENTERED AT 13:28:49 ON 27 JAN 2009

L83 2 S L82 AND L80
 L84 3 S L78 NOT L83
 L85 5 S L77 NOT L78,L83
 SEL DN 1 3 4
 L86 2 S L85 NOT E8-E10
 L87 7 S L80,L83,L84,L86
 L88 8 S L1-L11 AND L37
 L89 2 S L88 AND L54,L57,L74
 L90 7 S L87,L89
 L91 6 S L88 NOT L90

FILE 'REGISTRY' ENTERED AT 13:35:15 ON 27 JAN 2009

FILE 'HCAPLUS' ENTERED AT 13:35:19 ON 27 JAN 2009

L92 TRA L91 1- RN : 53 TERMS

FILE 'REGISTRY' ENTERED AT 13:35:19 ON 27 JAN 2009

L93 53 SEA L92
 L94 2 S L93 AND L48,L50,L75
 L95 0 S L93 AND L54,L57,L74
 L96 4 S L93 AND UNSPECIFIED

FILE 'REGISTRY' ENTERED AT 13:37:16 ON 27 JAN 2009

FILE 'HCAPLUS' ENTERED AT 13:37:40 ON 27 JAN 2009

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